

Claims

1. An injection molded conductor carrying means comprising a first supporting substrate consisting of a first plastic material able in principle to be metallized, on which by using injection molding a second supporting substrate is so formed that the first supporting substrate remains partially uncovered, the second supporting substrate consisting of a second plastic material in principle not able to be metallized while however being able to be activated by a laser beam, and an electrical conductor arrangement extending over the two supporting substrates, such electrical conductor arrangement consisting of a metallized layer deposited on uncovered areas of the first supporting substrate and on areas, activated by a laser beam, of the second supporting substrate.

2. The conductor carrying means as set forth in claim 1, wherein the conductor arrangement extends on the first supporting substrate on spring elements or connection components constituted by integral components of the first supporting substrate.

3. The conductor carrying means as set forth in claim 1, wherein the conductor arrangement is formed on the second supporting substrate as a fine conductor structure.

4. The conductor carrying means as set forth in claim 1, wherein first plastic material is one with the specification PA66-GF, PC/ABS or LCP (Vectra E820i-Pd), and in the case of the second supporting substrate it is a question of a plastic material with the designation PA6/6TMID, PBTMID or PPMID.

5. A method for the production of an injection molded conductor carrying means with the use of a dual component injection molding method, in the case of

which a first plastic material, which is in principle able to be metallized, and a second plastic material, which is in principle not able to be metallized but is able to be activated by a laser beam, are so formed or molded on each other that a substrate body is produced, which includes a first supporting substrate consisting of the first plastic material and a second supporting substrate partially covering the first supporting substrate consisting of the second plastic material, following which a metallized pattern is produced on the second supporting substrate by laser beam activation, which pattern at least partially adjoins one or more uncovered areas of the first supporting substrate and following which a metallized layer is deposited simultaneously on the metallization pattern and on the uncovered areas, such metallized layer being able to be utilized as an electrical conductor arrangement

6. The method as set forth in claim 5, wherein the metallization pattern adjoins pad-like uncovered areas of large size on the first supporting substrate.

7. The method as set forth in claim 5, wherein the first plastic material is one with the specification PA66-GF, PC/ABS or LCP (Vectra E820i-Pd), and as the second supporting substrate a plastic material with the PA6/6TMID, PBTMID or PPMID is employed.